
Contents

Preface	ix
Introduction. The Digital Revolution	xv
Chapter 1. Integrated Circuits	1
1.1. Integrated circuits: presentation	2
1.1.1. Logic circuits	2
1.1.2. Analog circuits	3
1.2. The invention of the “integrated circuit”	3
1.2.1. Precursors	3
1.2.2. Jack Kilby’s invention	5
1.2.3. Robert Noyce’s patent	9
1.2.4. Lebovec’s invention	13
1.3. Industrial developments	14
1.3.1. Hybrid circuits	14
1.3.2. Logic function integrated circuits	14
1.3.3. Microprocessors	19
1.3.4. Analog circuits	20
1.4. Integrated circuit technologies	25
1.4.1. Integrated circuit design and photomask production	25
1.4.2. The manufacturing process	25
1.4.3. The technologies	26
1.5. References	30

Chapter 2. Memories	35
2.1. Introduction	35
2.2. SRAM memories	36
2.2.1. Cells and their operation	36
2.2.2. History	40
2.2.3. Industrial developments	41
2.3. DRAM memories	43
2.3.1. Intel 1103 cell	43
2.3.2. The one transistor DRAM cell	44
2.4. Storage memories	47
2.4.1. ROM memories	47
2.4.2. EPROM and EEPROM memories	48
2.5. References	54
 Chapter 3. Liquid Crystal Displays	57
3.1. The TFT – A history	57
3.1.1. The Lilienfeld direct field-effect transistor	57
3.1.2. Welker's TFT	58
3.1.3. Bardeen, Brattain and Gibney's research on the direct field effect	58
3.1.4. Weimer's direct field-effect transistor	59
3.2. The amorphous silicon TFT	60
3.3. Liquid crystal displays	63
3.3.1. History	63
3.3.2. Structure and operation of a liquid crystal display	63
3.4. References	66
 Chapter 4. Solar Cells	67
4.1. Introduction	68
4.2. Silicon: the material of solar cells	69
4.3. History	71
4.4. Solar radiation and its absorption	75
4.4.1. Solar radiation	75
4.4.2. Absorption of light energy	76
4.4.3. Quantum efficiency	78
4.5. Crystalline silicon solar cells	79
4.5.1. Manufacturing technology	79
4.5.2. Physical basis of operation	79
4.5.3. Characteristic curve	81
4.5.4. Conversion efficiency from solar energy to electricity	84

4.6. Action of metallic impurities on the solar conversion efficiency	85
4.6.1. Lifetimes and diffusion lengths of “electrons”: influence of doping. The gettering effect.	85
4.6.2. Monocrystalline cells	86
4.6.3. Polycrystalline cells	88
4.7. Amorphous silicon solar cells	89
4.8. Solar silicon manufacturing processes	90
4.8.1. Production of polysilicon (Si-EG) in a fluidized-bed reactor	90
4.8.2. Production of columnar polycrystalline ingots.	91
4.8.3. Purification of metallurgical silicon by metallurgical processes	93
4.9. References	94
 Chapter 5. Digital Photographic Sensors	97
5.1. Introduction.	98
5.2. CCD sensors	98
5.2.1. Features.	98
5.2.2. CCD pixel structure and quantum efficiency.	99
5.2.3. CCD cell structure and charge transfer	102
5.2.4. Reading circuit	103
5.3. CMOS-APS sensors with active pixels	104
5.4. History.	105
5.5. References	108
 Chapter 6. Microelectromechanical Systems	111
6.1. Parts for precision mechanics	112
6.2. MEMS: sensors and actuators	113
6.2.1. Presentation	113
6.2.2. History	115
6.2.3. Silicon: the material of MEMS	116
6.3. The physical basis of MEMS operation	118
6.3.1. Sensors	118
6.3.2. Actuators	122
6.3.3. Microelectromechanical resonators	124
6.4. Some examples of MEMS	126
6.4.1. Piezoresistive pressure sensor	126
6.4.2. Gravimetric resonant sensor with vibrating beam.	127
6.4.3. Microphone: capacitive sensor	127
6.4.4 Inertial MEMS: accelerometers and gyroscopes	128
6.4.5. Micromotors.	132

6.5. MEMS manufacturing technologies	134
6.5.1. Bulk micromachining	134
6.5.2. Surface micromachining.	137
6.5.3. Manufacturing processing sequence of a lateral resonant structure. .	137
6.6. References	139
 Index of Names	143
 Index of Terms	145
 Summary of Volume 1	149